

AMENDMENTS TO THE CLAIMS:

Claims 1-19 (canceled).

20. (New) A polishing apparatus comprising:
a polishing table having a polishing surface;
a top ring for pressing a workpiece against said polishing surface at a predetermined pressure so as to polish the workpiece; and
at least two dressing units for dressing said polishing surface by being brought into contact with said polishing surface,
wherein said at least two dressing units are to dress said polishing surface at different times, respectively.

21. (New) The polishing apparatus according to claim 20, wherein
said at least two dressing units include different dressers, respectively.

22. (New) The polishing apparatus according to claim 20, wherein
at least one of said at least two dressing units includes a dresser having a diameter greater than a diameter of the workpiece to be polished, and
at least one of said at least two dressing units includes a dresser having a diameter smaller than the diameter of the workpiece to be polished.

23. (New) The polishing apparatus according to claim 22, wherein
said dresser having a diameter greater than a diameter of the workpiece to be polished comprises one of a ring-shaped dresser and a disk-shaped dresser, and
said dresser having a diameter smaller than the diameter of the workpiece to be polished comprises one of a ring-shaped dresser and a disk-shaped dresser.

24. (New) The polishing apparatus according to claim 20, wherein said at least two dressing units are for dressing said polishing surface by re-generating said polishing surface.

25. (New) The polishing apparatus according to claim 20, wherein said at least two dressing units are of a material that is different than that of the workpiece.

26. (New) The polishing apparatus according to claim 20, wherein said at least two dressing units are not co-axial with one another.

27. (New) The polishing apparatus according to claim 20, wherein said at least two dressing units are of different material relative to one another.

28. (New) The polishing apparatus according to claim 20, wherein there are at least twice as many dressing units as there are top rings.

29. (New) The polishing apparatus according to claim 20, wherein said at least two dressing units each have a contact surface for contacting said polishing surface during dressing of said polishing surface.

30. (New) A polishing apparatus comprising:
a polishing table having a polishing surface;
a top ring for pressing a workpiece against said polishing surface so as to polish the workpiece; and
a dressing unit having a first dresser for dressing said polishing surface while the workpiece is being polished, and also having a second dresser for dressing said polishing surface while the workpiece is not being polished.

31. (New) The polishing apparatus according to claim 30, wherein
said first dresser is for dressing said polishing surface only during polishing of the workpiece,
and
said second dresser is for dressing said polishing surface only while the workpiece is not being
polished.

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32. (New) A polishing apparatus for polishing a workpiece, comprising:
a table for providing a polishing surface;
a first dresser having a contact surface for contacting said polishing surface during a first
dressing operation;
a second dresser having a contact surface for contacting said polishing surface during a second
dressing operation; and
an atomizer for spraying a fluid on said polishing surface to remove a polishing waste present
on said polishing surface,
wherein said first dresser and said second dresser are to perform said first dressing operation
and said second dressing operation at different times, respectively.

33. (New) A polishing apparatus for polishing a workpiece, comprising:
a table for providing a polishing surface;
a first dresser having a contact surface for contacting said polishing surface during a first
dressing operation;
a second dresser having a contact surface for contacting said polishing surface during a second
dressing operation;
a sensor for measuring a profile of said polishing surface; and
a controller for controlling a dressing process of said first dresser,
wherein said first dresser and said second dresser are to perform said first dressing operation
and said second dressing operation at different times, respectively.

34. (New) A polishing apparatus comprising:
a polishing table having a polishing surface;
a top ring for pressing a workpiece against said polishing surface at a predetermined pressure so as to polish the workpiece; and
at least two dressers for dressing said polishing surface,
wherein one of said at least two dressers is to perform an initial surface conditioning of said polishing surface at a time prior to polishing of any workpiece, and another of said at least two dressers is for dressing said polishing surface after the workpiece has been polished.

35. (New) The polishing apparatus according to claim 34, wherein
said one of said at least two dressers is for performing the initial surface conditioning of said polishing surface only at the time prior to polishing of any workpiece, and
said another of said at least two dressers is for dressing said polishing surface only after a workpiece has been polished.

36. (New) The polishing apparatus according to claim 34, wherein
said at least two dressers are different in size relative to one another.

37. (New) The polishing apparatus according to claim 34, wherein
at least one of said at least two dressers has a diameter greater than a diameter of the workpiece to be polished, and
at least one of said at least two dressers has a diameter smaller than the diameter of the workpiece to be polished.

38. (New) The polishing apparatus according to claim 34, wherein
one of said at least two dressers is to move across said polishing surface while dressing said polishing surface.

39. (New) The polishing apparatus according to claim 34, wherein at least one of said at least two dressers is to dress said polishing surface while the workpiece is not being polished.

40. (New) The polishing apparatus according to claim 34, wherein said at least two dressers comprise diamond dressers.

41. (New) The polishing apparatus according to claim 34, wherein said one of said at least two dressers comprises a diamond dresser, and said another of said at least two dressers comprises a brush dresser.

42. (New) The polishing apparatus according to claim 34, wherein one of said at least two dressers is to have at least one of its swing speed, rotational speed, and pressing load controlled based on a profile of a surface, to be polished, of the workpiece.

43. (New) The polishing apparatus according to claim 34, wherein one of said at least two dressers is to have at least one of its swing speed, rotational speed, and pressing load controlled based on a profile of said polishing surface.

44. (New) The polishing apparatus according to claim 34, wherein said one of said at least two dressers is to dress said polishing surface after a plurality of workpieces has been polished.

45. (New) The polishing apparatus according to claim 34, wherein said one of said at least two dressers is to dress said polishing surface when a polishing performance is not properly maintained.

46. (New) The polishing apparatus according to claim 45, wherein said one of said at least two dressers is to dress said polishing surface when the polishing performance is determined to not be properly maintained based on a profile of a surface, to be polished, of the workpiece not meeting a predetermined level requirement

47. (New) The polishing apparatus according to claim 34, further comprising: an atomizer for spraying a fluid onto said polishing surface so as to remove a polishing waste present on said polishing surface.

48. (New) The polishing apparatus according to claim 47, wherein said atomizer is to spray a fluid composed of a mixture of gas and liquid.

49. (New) The polishing apparatus according to claim 47, wherein said atomizer is for spraying the fluid onto said polishing surface while the workpiece is not being polished.

50. (New) The polishing apparatus according to claim 47, wherein said atomizer is for spraying the fluid onto said polishing surface while said polishing surface is being dressed.

Excluded